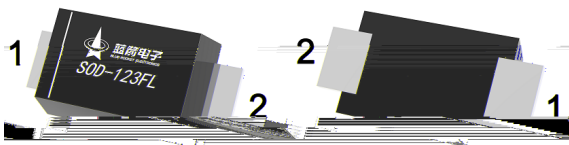
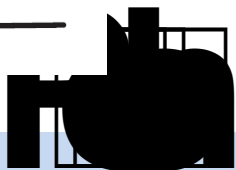




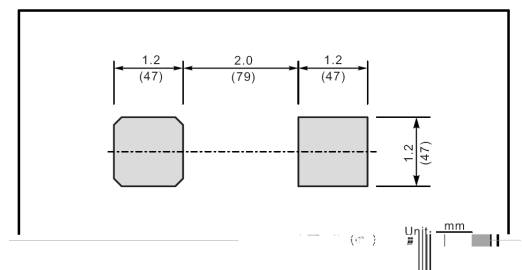
3.0A

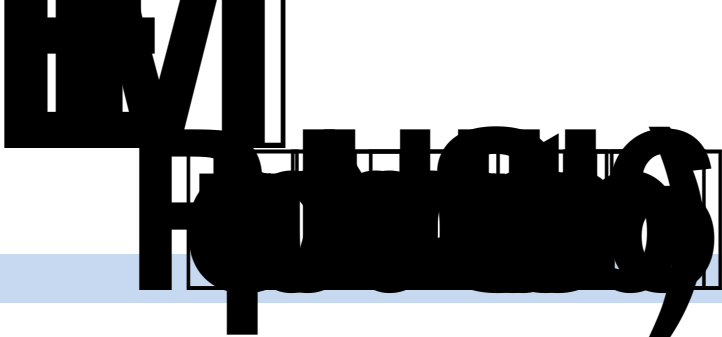


PIN	DESCRIPTION
1	Cathode
2	Anode



The recommended mounting pad size





	()		
)			
	θ		℃
			℃
			℃



			数值	
		℃		
		℃		

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Fig.1 Forward Current Derating Curve

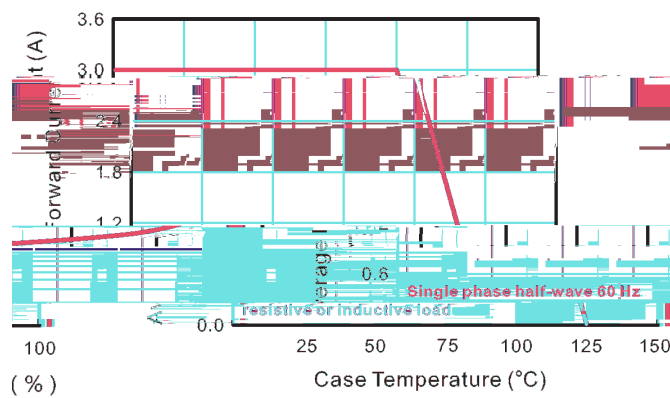


Fig.2 Typical Reverse Characteristics

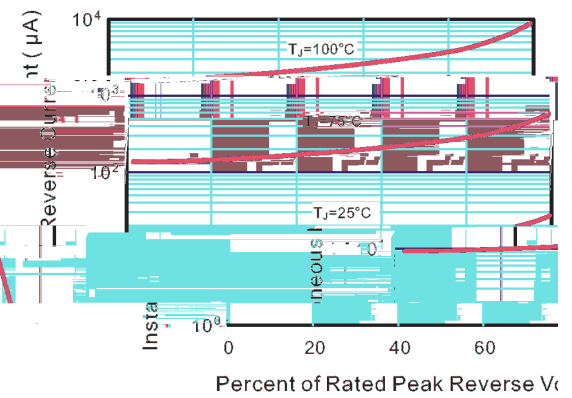


Fig.3 Typical Forward Characteristic

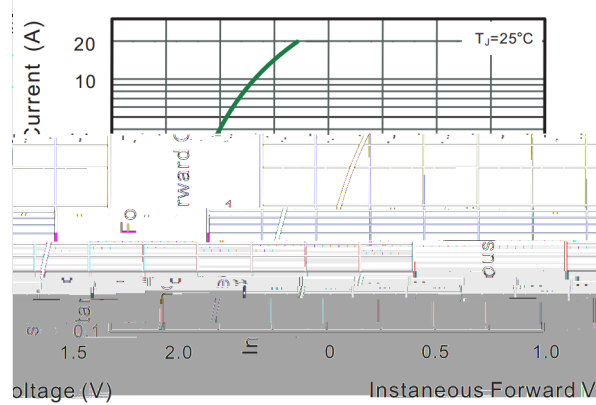


Fig.4 Typical Junction Capacitance

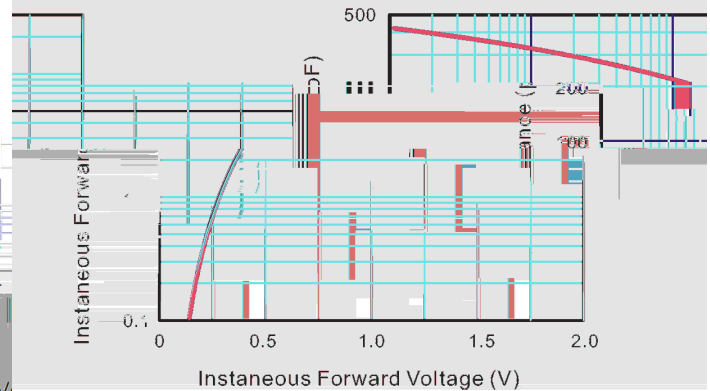


Fig.6 Typical Transient Thermal Impedance

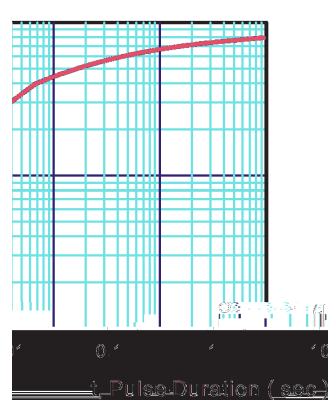
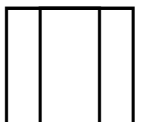
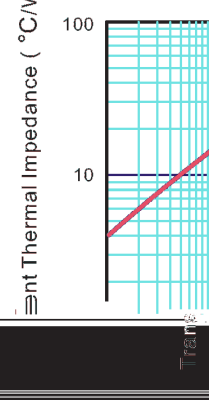
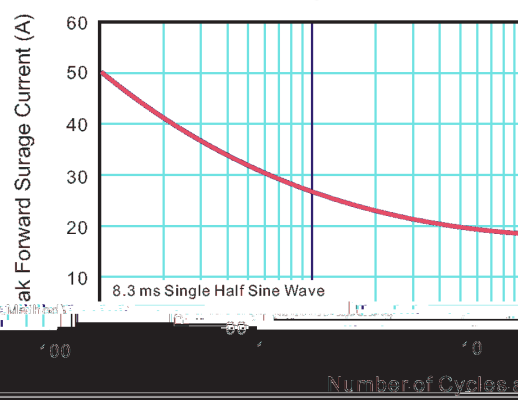
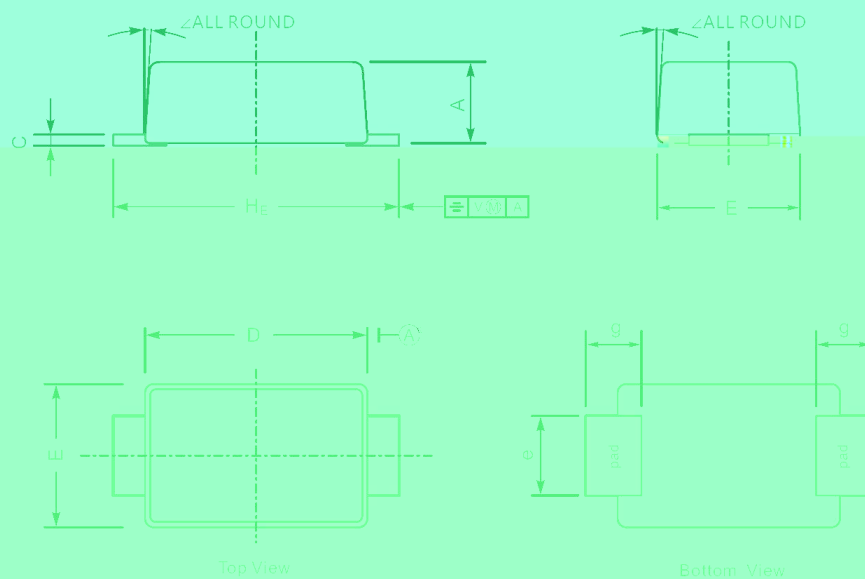


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

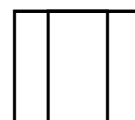


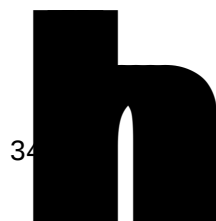
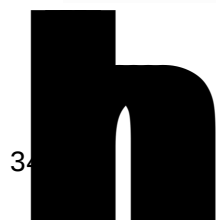


SOD-123FL



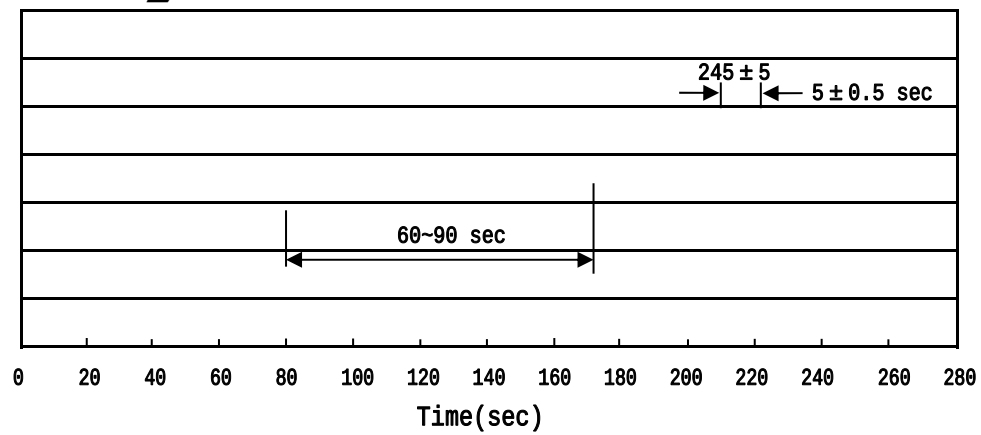
UNIT		A	C	D	E	e	g	H _E	$\angle$
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	







Temperature Profile for IR Reflow Soldering(Pb-Free)



	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
			/	/	/	"		

